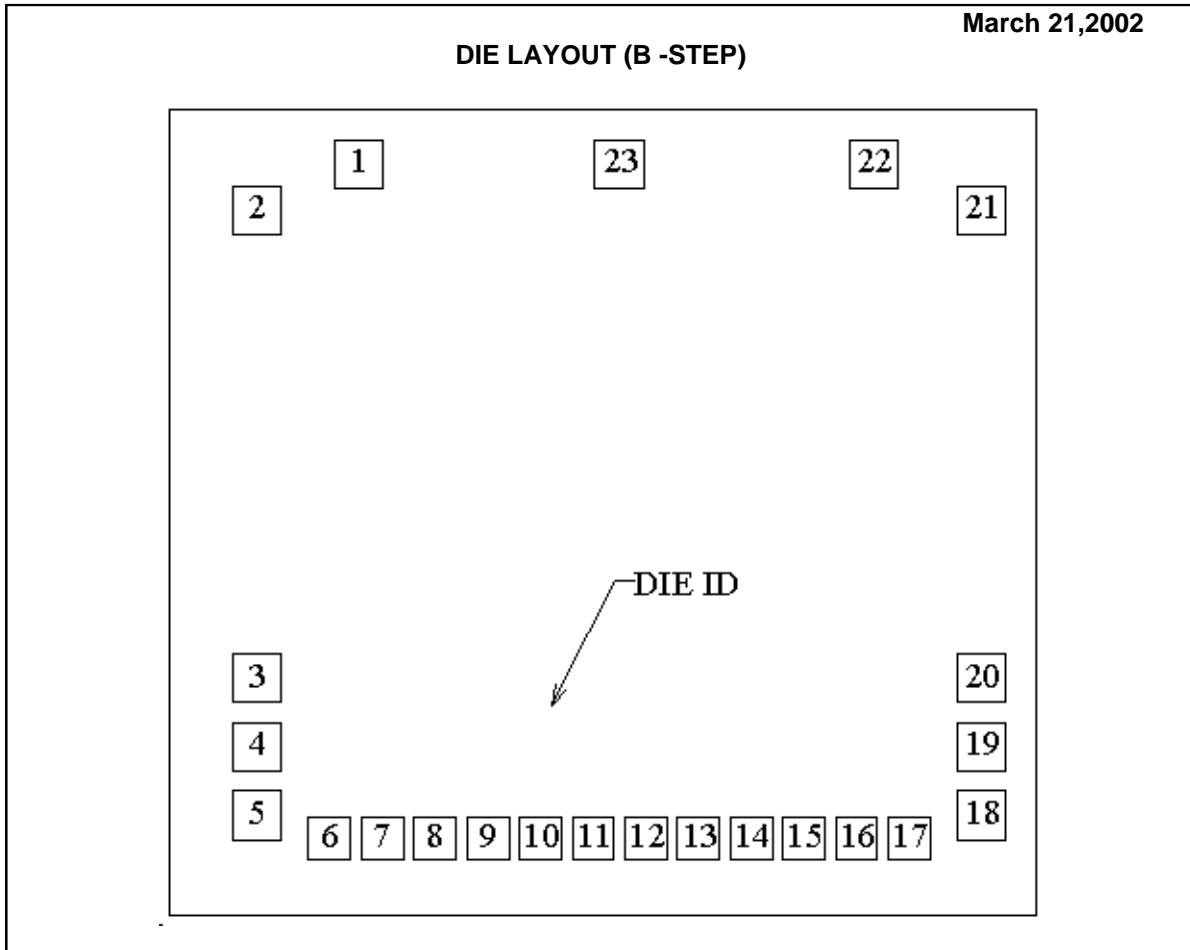


LMC6482M MD8 MW8
CMOS DUAL RAIL-TO-RAIL INPUT AND OUTPUT OPERATIONAL AMPLIFIER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMC6482B	Bond Pad Opening Size (min)	100µm x 100µm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1676µm x 1803µm 66mils x 71mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	107µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES		PAD SIZE		
		X	Y	X	Y	
OUTA	1	-500	714	100	x	100
IN A -	2	-709	619	100	x	100
IN A +	3	-709	-340	100	x	100
NC	4	-709	-480	100	x	100
V -	5	-709	-620	100	x	100
NC	6	-560	-667	86	x	86
NC	7	-452	-667	86	x	86
NC	8	-344	-667	86	x	86
NC	9	-236	-667	86	x	86
NC	10	-128	-667	86	x	86
NC	11	-20	-667	86	x	86
NC	12	88	-667	86	x	86
NC	13	196	-667	86	x	86
NC	14	304	-667	86	x	86
NC	15	412	-667	86	x	86
NC	16	520	-667	86	x	86
NC	17	628	-667	86	x	86
NC	18	777	-620	100	x	100
NC	19	777	-480	100	x	100
IN B +	20	777	-340	100	x	100
IN B -	21	777	619	100	x	100
OUT B	22	555	714	100	x	100
V +	23	34	714	100	x	100

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IN U.S.A.

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Fax: 1 207 541 6140

IN EUROPE

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Fax: 49 (0) 8141 351470

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